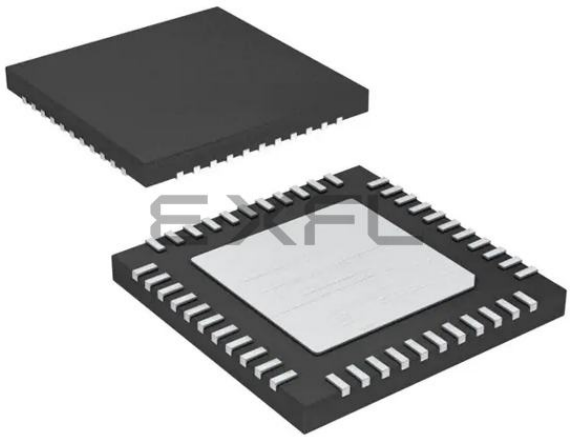
Microchip Technology - PIC32MX254F128DT-V/ML Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, HLVD, I²S, POR, PWM, WDT
Number of I/O	34
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx254f128dt-v-ml

TABLE 4: PIN NAMES FOR 28-PIN GENERAL PURPOSE DEVICES WITHOUT VBAT

28-PIN SOIC (TOP VIEW)(1,2,3)

1 28

SOIC

PIC32MX154F128B
PIC32MX174F256B

Pin #	Full Pin Name	Pin #	Full Pin Name
1	$\overline{\text{MCLR}}$	15	PGEC3/RPB6/ASCL2/PMD6/RB6
2	VREF+/AN0/C3INC/RPA0/ASDA1/CTED1/PMA1/RA0	16	TDI/RPB7/CTED3/PMD5/INT0/RB7
3	VREF-/AN1/RPA1/ASCL1/CTED2/RA1	17	TCK/RPB8/SCL1/CTED10/PMD4/RB8
4	PGED2/AN2/C1IND/C2INB/C3IND/RPB0/RB0	18	TDO/RPB9/SDA1/CTED4/PMD3/RB9
5	PGEC2/AN3/C1INC/C2INA/LVDIN/RPB1/CTED12//RB1	19	VSS
6	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2	20	VCAP
7	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3	21	PGED1/RPB10/CTED11/PMD2/RB10
8	VSS	22	PGEC1/TMS/RPB11/PMD1/RB11
9	OSC1/CLKI/RPA2/RA2	23	AN12/PMD0/RB12
10	OSC2/CLKO/RPA3/PMA0/RA3	24	AN11/RPB13/CTPLS/PMRD/RB13
11	SOSCI/RPB4/RB4(4)	25	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14
12	SOSCO/RPA4/T1CK/CTED9/RA4	26	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
13	VDD	27	AVSS
14	PGED3/RPB5/ASDA2/PMD7/RB5	28	AVDD

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RBx) can be used as a change notification pin (CNAx-CNBx). See **12.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

4: This is an input-only pin.

TABLE 12: PIN NAMES FOR 44-PIN GENERAL PURPOSE DEVICES WITHOUT VBAT

44-PIN QFN AND TQFP (TOP VIEW)(1,2,3,5)

PIC32MX154F128D
PIC32MX174F256D

44 1 44 1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMA7/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMA2/RB3
3	RPC7/PMCS1/RC7	25	AN6/RPC0/RC0
4	RPC8/PMD5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMD6/RC9	27	AN8/RPC2/PMWR/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED1/RPB10/CTED11/PMA8/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC1/TMS/RPB11/PMA9/RB11	31	OSC2/CLKO/RPA3/RA3
10	AN12/PMD0/RB12	32	TDO/RPA8/PMD2/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/CTED11/RB4
12	PGED4/PMA10/RA10	34	SOSCO/RPA4/T1CK/RA4
13	PGEC4/TCK/CTED8/PMD3/RA7	35	TDI/RPA9/PMD1/RA9
14	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/RB14	36	RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMA0/RB15	37	RPC4/PMD4/RC4
16	AVSS	38	RPC5/PMD7/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	VREF+/AN0/C3INC/RPA0/ASDA1/CTED1/RA0	41	PGED3/RPB5/ASDA2/PMA3/RB5
20	VREF-/AN1/RPA1/ASCL1/CTED2/RA1	42	PGEC3/RPB6/ASCL2/PMA6/RB6
21	PGED2/AN2/C1IND/C2INB/C3IND/RPB0/RB0	43	RPB7/CTED3/PMA5/INT0/RB7
22	PGEC2/AN3/C1INC/C2INA/LVDIN/RPB1/CTED12/RB1	44	RPB8/SCL1/CTED10/PMA4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **12.3 "Peripheral Pin Select"** for restrictions.
2: Every I/O port pin (RAx-RBx) can be used as a change notification pin (CNAx-CNBx). See **12.0 "I/O Ports"** for more information.
3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
4: Shaded pins are 5V tolerant.

TABLE 1-2: OSCILLATOR PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SOIC	44-pin QFN/ TQFP			
Oscillators						
CLKI	6	9	30	I	ST/CMOS	External clock source input. Always associated with OSC1 pin function.
CLKO	7	10	31	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	6	9	30	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	7	10	31	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	8	11	33	I	ST/CMOS	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	9	12	34	O	—	32.768 kHz low-power oscillator crystal output.
REFCLKI	PPS	PPS	PPS	I	ST	Reference Input Clock
REFCLKO	PPS	PPS	PPS	O	—	Reference Output Clock

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

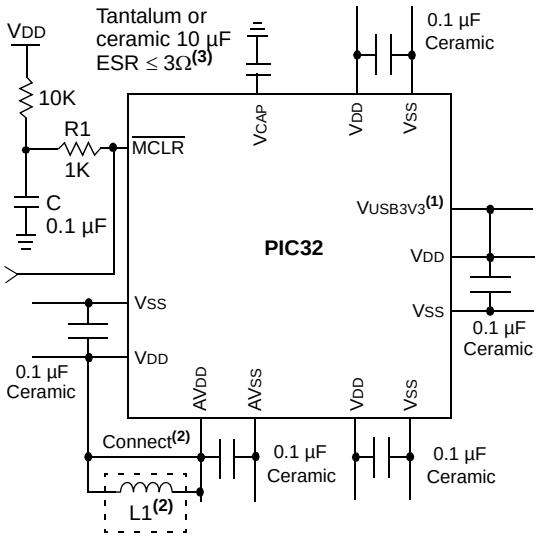
TABLE 1-3: IC1 THROUGH IC5 PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SOIC	44-pin QFN/ TQFP			
Input Capture						
IC1	PPS	PPS	PPS	I	ST	Input Capture Input 1-5
IC2	PPS	PPS	PPS	I	ST	
IC3	PPS	PPS	PPS	I	ST	
IC4	PPS	PPS	PPS	I	ST	
IC5	PPS	PPS	PPS	I	ST	

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: If the USB module is not used, this pin must be connected to VDD.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

1: Aluminum or electrolytic capacitors should not be used. ESR ≤ 3Ω from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (3 ohm) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a CEFC capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **33.0 "Electrical Characteristics"** for additional information on CEFC specifications.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

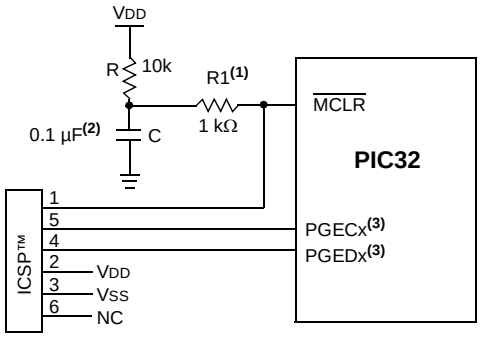
- Device Reset
- Device programming and debugging

Pulling The MCLR pin low generates a device Reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: 470Ω ≤ R1 ≤ 1Ω will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met without interfering with the Debug/Programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- CIN = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- COUT = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}] \} + \text{estimated oscillator PCB stray capacitance}$$

$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5] \} + 2.5\ pF$$

$$= \{([20][20]) / [40] \} + 2.5$$

$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 13 pF in this example for Primary Oscillator crystals “C1” and “C2”.

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

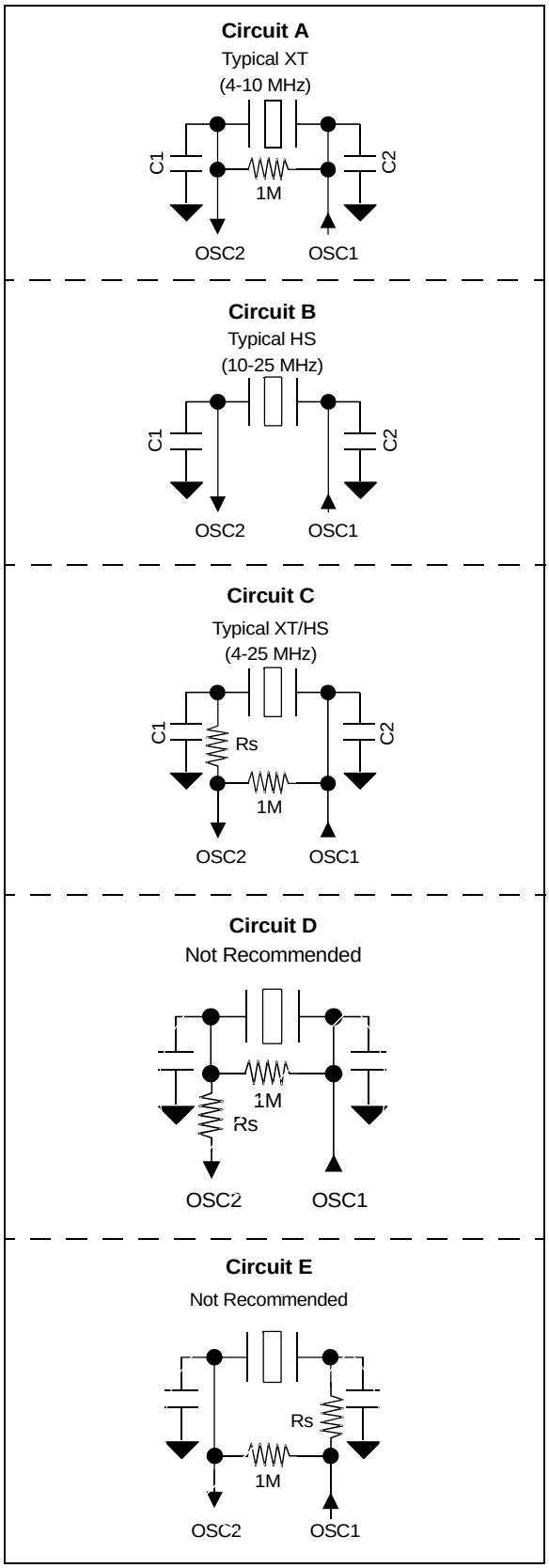
- Select a crystal with a lower “minimum” power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing “ESR” rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note: Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit “C” in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~VDD-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 *“PICmicro® Microcontroller Oscillator Design Guide”*
- AN826 *“Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices”*
- AN849 *“Basic PICmicro® Oscillator Design”*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



NOTES:

REGISTER 7-6: IPCx: INTERRUPT PRIORITY CONTROL REGISTER (CONTINUED)

bit 9-8 **IS01<1:0>:** Interrupt Subpriority bits
11 = Interrupt subpriority is 3
10 = Interrupt subpriority is 2
01 = Interrupt subpriority is 1
00 = Interrupt subpriority is 0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-2 **IP00<2:0>:** Interrupt Priority bits
111 = Interrupt priority is 7
•
•
•
010 = Interrupt priority is 2
001 = Interrupt priority is 1
000 = Interrupt is disabled

bit 1-0 **IS00<1:0>:** Interrupt Subpriority bits
11 = Interrupt subpriority is 3
10 = Interrupt subpriority is 2
01 = Interrupt subpriority is 1
00 = Interrupt subpriority is 0

Note:	This register represents a generic definition of the IPCx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 9-1: DMACON: DMA CONTROLLER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0
	ON(1)	—	—	SUSPEND	DMABUSY	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** DMA On bit(1)
- 1 = DMA module is enabled
- 0 = DMA module is disabled

bit 14-13 **Unimplemented:** Read as '0'

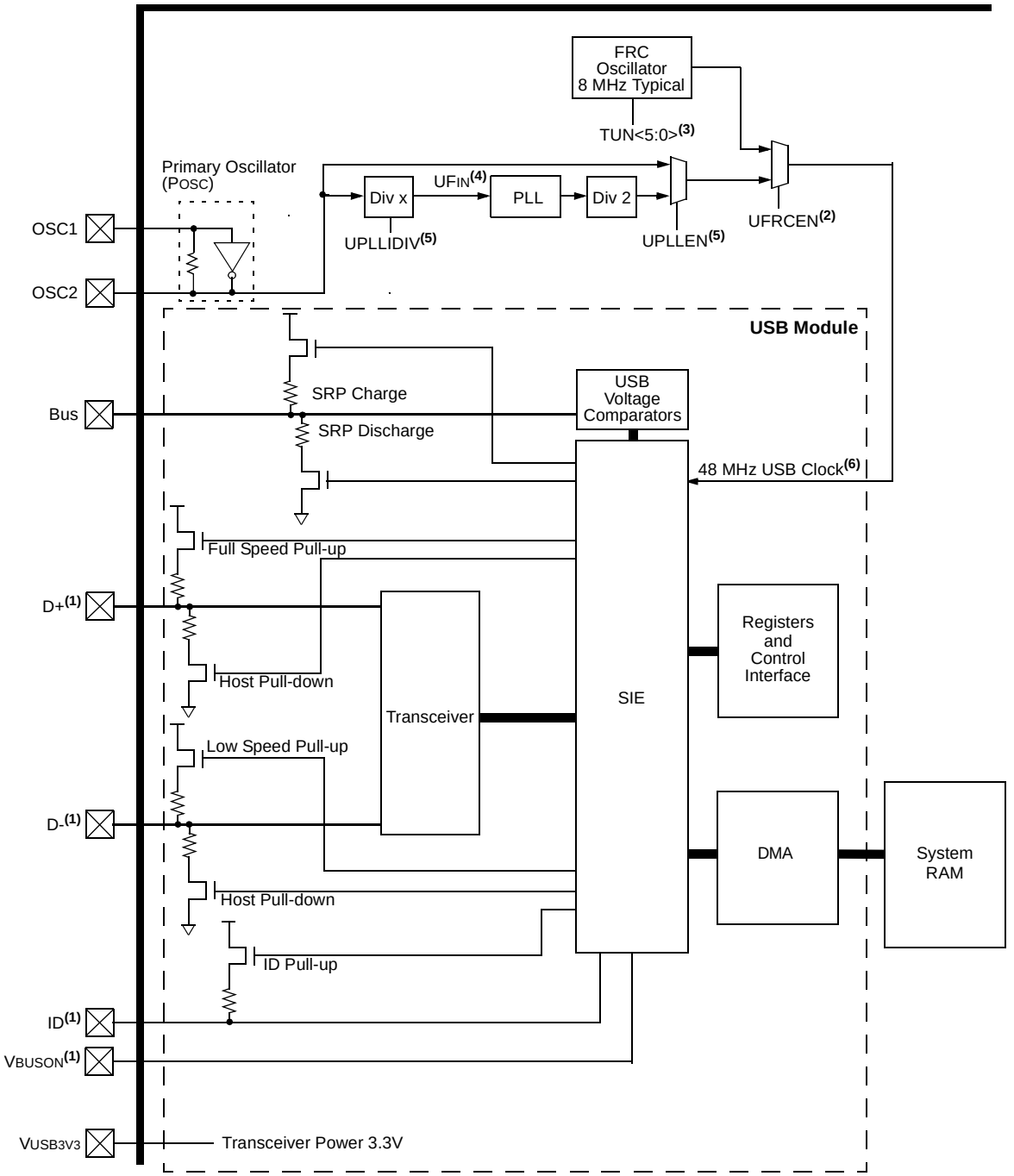
bit 12 **SUSPEND:** DMA Suspend bit
- 1 = DMA transfers are suspended to allow CPU uninterrupted access to data bus
- 0 = DMA operates normally

bit 11 **DMABUSY:** DMA Module Busy bit
- 1 = DMA module is active
- 0 = DMA module is disabled and not actively transferring data

bit 10-0 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

FIGURE 11-1: PIC32MX1XX/2XX 28/44-PIN XLP FAMILY FAMILY USB INTERFACE DIAGRAM



Note 1: Pins can be used as digital input/output when USB is not enabled.
2: This bit field is contained in the OSCCON register.
3: This bit field is contained in the OSCTRM register.
4: USB PLL UFIN requirements: 4 MHz.
5: This bit field is contained in the DEVCFG2 register.
6: A 48 MHz clock is required for proper USB operation.

REGISTER 11-14: U1FRMH: USB FRAME NUMBER HIGH REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	R-0	R-0	R-0
	—	—	—	—	—	FRMH<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-3 **Unimplemented:** Read as '0'

bit 2-0 **FRMH<2:0>:** The Upper 3 bits of the Frame Numbers bits
The register bits are updated with the current frame number whenever a SOF TOKEN is received.

REGISTER 11-15: U1TOK: USB TOKEN REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	PID<3:0>(1)				EP<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-4 **PID<3:0>:** Token Type Indicator bits(1)
1101 = SETUP (TX) token type transaction
1001 = IN (RX) token type transaction
0001 = OUT (TX) token type transaction
Note: All other values are reserved and must not be used.

bit 3-0 **EP<3:0>:** Token Command Endpoint Address bits
The four bit value must specify a valid endpoint.

Note 1: All other values are reserved and must not be used.

18.1 Output Compare Control Registers

TABLE 18-1: OUTPUT COMPARE 1-OUTPUT COMPARE 5 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	OC1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3010	OC1R	31:16	OC1R<31:0>																xxxx
		15:0																	xxxx
3020	OC1RS	31:16	OC1RS<31:0>																xxxx
		15:0																	xxxx
3200	OC2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3210	OC2R	31:16	OC2R<31:0>																xxxx
		15:0																	xxxx
3220	OC2RS	31:16	OC2RS<31:0>																xxxx
		15:0																	xxxx
3400	OC3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3410	OC3R	31:16	OC3R<31:0>																xxxx
		15:0																	xxxx
3420	OC3RS	31:16	OC3RS<31:0>																xxxx
		15:0																	xxxx
3600	OC4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3610	OC4R	31:16	OC4R<31:0>																xxxx
		15:0																	xxxx
3620	OC4RS	31:16	OC4RS<31:0>																xxxx
		15:0																	xxxx
3800	OC5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3810	OC5R	31:16	OC5R<31:0>																xxxx
		15:0																	xxxx
3820	OC5RS	31:16	OC5RS<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **12.2 "CLR, SET and INV Registers"** for more information.

REGISTER 22-7: PMRADDR: PARALLEL PORT READ ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	—	RCS1	—	—	—	RADDR<10:8>		
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	RADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-15 **Unimplemented:** Read as '0'

bit 14 **RCS1:** Chip Select 1 bit
- 1 = Chip Select 1 is active
- 0 = Chip Select 1 is inactive (RADDR14 function is selected)

bit 13-11 **Unimplemented:** Read as '0'

bit 10-0 **RADDR<13:0>:** Address bits

Note: This register is only used when the DUALBUF bit (PMCON<17>) is set to '1'.

REGISTER 24-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit(2)
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit(3)
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ '0', this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

REGISTER 24-4: AD1CHS: ADC INPUT SELECT REGISTER (CONTINUED)

bit 20-16 **CH0SA<4:0>:** Positive Input Select bits for Sample A Multiplexer Setting

11111 = Reserved
•
•
•
10010 = Reserved
10001 = Channel 0 positive input is $V_{DD}/2$
10000 = Channel 0 positive input is V_{BAT}
01111 = Reserved
01110 = Channel 0 positive input is IV_{REF} **(1)**
01101 = Channel 0 positive input is CTMU temperature sensor (CTMUT) **(2)**
01100 = Channel 0 positive input is AN12 **(3)**
•
•
•
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

bit 15-0 **Unimplemented:** Read as '0'

Note 1: See **26.0 "Comparator Voltage Reference (CV_{REF})"** for more information.

2: See **28.0 "Charge Time Measurement Unit (CTMU)"** for more information.

3: AN12 is only available on 44-pin devices. AN6-AN8 are not available on 28-pin devices.

REGISTER 25-1: CMXCON: COMPARATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	R-0
	ON(1)	COE	CPOL(2)	—	—	—	—	COUT
7:0	R/W-1	R/W-1	U-0	R/W-0	U-0	U-0	R/W-1	R/W-1
	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Comparator ON bit(1)
- 1 = Module is enabled. Setting this bit does not affect the other bits in this register
- 0 = Module is disabled and does not consume current. Clearing this bit does not affect the other bits in this register

bit 14 **COE:** Comparator Output Enable bit
- 1 = Comparator output is driven on the output CxOUT pin
- 0 = Comparator output is not driven on the output CxOUT pin

bit 13 **CPOL:** Comparator Output Inversion bit(2)
- 1 = Output is inverted
- 0 = Output is not inverted

bit 12-9 **Unimplemented:** Read as '0'

bit 8 **COUT:** Comparator Output bit
- 1 = Output of the Comparator is a '1'
- 0 = Output of the Comparator is a '0'

bit 7-6 **EVPOL<1:0>:** Interrupt Event Polarity Select bits
- 11 = Comparator interrupt is generated on a low-to-high or high-to-low transition of the comparator output
- 10 = Comparator interrupt is generated on a high-to-low transition of the comparator output
- 01 = Comparator interrupt is generated on a low-to-high transition of the comparator output
- 00 = Comparator interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Positive Input Configure bit
- 1 = Comparator non-inverting input is connected to the internal CVREF
- 0 = Comparator non-inverting input is connected to the CXINA pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Negative Input Select bits for Comparator
- 11 = Comparator inverting input is connected to the IVREF
- 10 = Comparator inverting input is connected to the CxIND pin
- 01 = Comparator inverting input is connected to the CxINC pin
- 00 = Comparator inverting input is connected to the CxINB pin

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: Setting this bit will invert the signal to the comparator interrupt generator as well. This will result in an interrupt being generated on the opposite edge from the one selected by EVPOL<1:0>.

29.3.4 DEEP SLEEP MODE

Deep Sleep mode brings the device into its lowest power consumption state without requiring the use of external switches to remove power from the device.

- **Deep Sleep**
  In this mode, the CPU, RAM and most peripherals are powered down. Power is maintained to the DSGPR0 register and one or more of the RTCC, DSWDT and DSGPR1 through DSGPR32 registers.

Which of these peripherals is active depends on the state of the following register bits when Deep Sleep mode is entered:

- **RTCDIS (DSCON<12>)**
  This bit must be set to disable the RTCC in Deep Sleep mode (see Register 29-1).
- **DSWDTEN (DEVCFG2<30>)**
  This Configuration bit must be set to enable the DSWDT register in Deep Sleep mode (see Register 30-3)
- **DSGPREN (DSCON<13>)**
  This bit must be set to enable the DSGPR1 through DSGPR32 registers in Deep Sleep mode (see Register 29-1).

Note:	The Deep Sleep Control registers can only be accessed after the system unlock sequence has been performed. In addition, the Deep Sleep Control registers must be written twice.

In addition to the conditionally enabled peripherals described above, the $\overline{\text{MCLR}}$ filter and INT0 pin are enabled in Deep Sleep mode.

29.3.5 VBAT MODE

VBAT mode is similar to Deep Sleep mode, except that the device is powered from the V_{BAT} pin. VBAT mode is controlled strictly by hardware, without any software intervention. VBAT mode is initiated when V_{DD} falls below V_{POR} (refer to the **33.0 "Electrical Characteristics"** for definitions of V_{DD} and V_{POR}). An external power source must be connected to the V_{BAT} pin before power is removed from V_{DD} to enter VBAT mode. VBAT is the lowest battery-powered mode that can maintain an RTCC. Wake-up from VBAT mode can only occur when V_{DD} is reapplied. The wake-up will appear to be a POR to the rest of the device.

In VBAT mode, the Deep Sleep Watchdog Timer is disabled. The RTCC and DSGPR1 through DSGPR32 registers may be enabled or disabled depending on the state of the RTCDIS bit (DSCON<12>) and the DSGPREN bit (DSCON<13>), respectively. Deep Sleep Persistent General Purpose Register 0 (DSGPR0) is always enabled in VBAT mode.

29.3.6 XLP POWER-SAVING MODES

Figure 29-1 shows a block diagram of the system domain for XLP devices and the related power-saving features. The various blocks are controlled by the following Configuration bit settings and SFRs:

- DSBOREN (DEVCFG2<20>)
- DSEN (DSCON<15>)
- DSGPREN (DSCON<13>)
- DSWDTEN (DEVCFG2<30>)
- DSWDTOSC (DEVCFG2<29>)
- RELEASE (DSCON<0>)
- RTCCLKSEL (RTCCON <9:8>)
- RTCDIS (DSCON<12>)
- SLPEN (OSCCON<4>)
- VREGS (PWRCON<0>)

REGISTER 30-6: DEVID: DEVICE AND REVISION ID REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0>(1)				DEVID<27:24>(1)			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16>(1)							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8>(1)							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0>(1)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

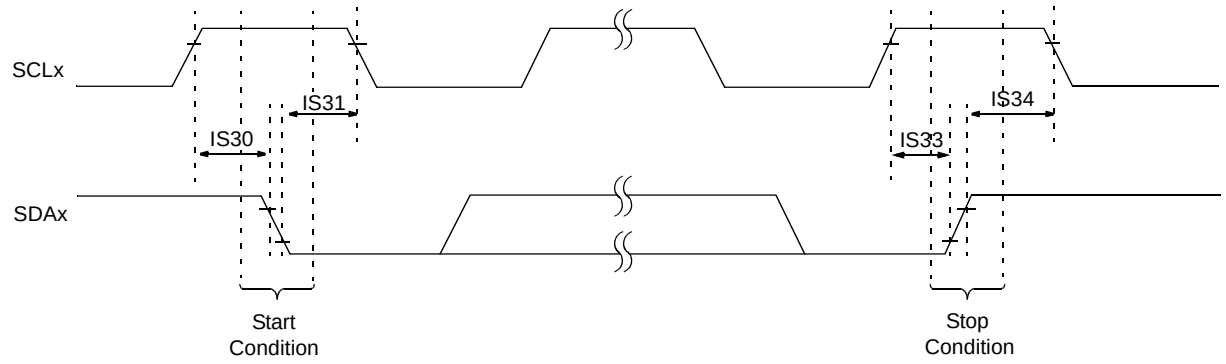
bit 31-28 **VER<3:0>:** Revision Identifier bits(1)

bit 27-0 **DEVID<27:0>:** Device ID bits(1)

Note 1: See the *"PIC32 Flash Programming Specification"* (DS60001145) for a list of Revision and Device ID values.

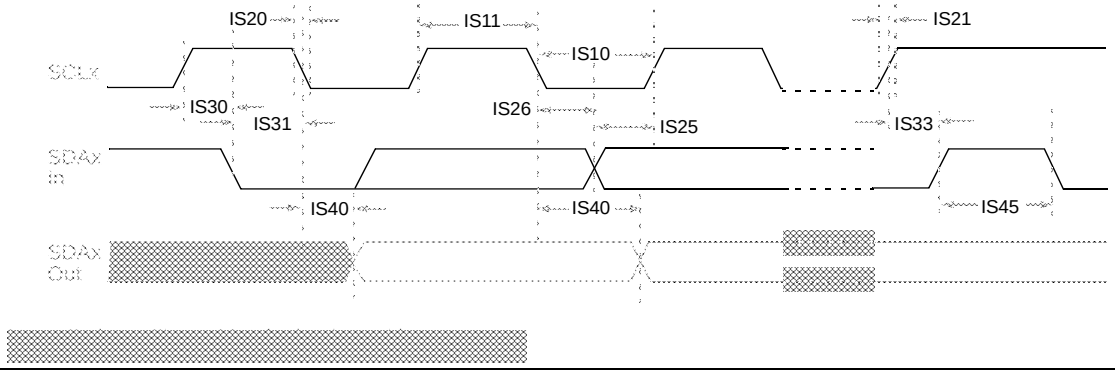
NOTES:

FIGURE 33-16: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)



Note: Refer to Figure 33-1 for load conditions.

FIGURE 33-17: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)



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ISBN: 978-1-5224-0583-2